

MULTI-LAYERED SEMICONDUCTOR DEVICE AND METHOD FOR
PRODUCING THE SAME

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ABSTRACT OF THE DISCLOSURE

10 To minimize a size of a semiconductor device and
reduce a thickness thereof as well as improve the yield
and lower the production cost in the production of a
semiconductor package, a multi-layered semiconductor
device is provided, wherein a film-like semiconductor
15 package (10) incorporating therein a semiconductor chip
(12) is disposed in a package accommodation opening (11a)
of a circuit pattern layer to form a circuit board. A
plurality of such circuit boards are layered together to
electrically connect circuit patterns (13) of the circuit
boards with each other via a low melting point metal (14)
20 or lead beam bonding (13b).

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